



NC-560-LF, Lead Free Solder Paste

Product Data Sheet

Product Highlights

- ROL0 flux classification
- Exceptional print definition at high printing speeds up to 125mm/sec
- Excellent wetting on all common finishes including Ni/Au
- Clear residue
- Low voiding
- Reduces head in pillow defects
- RoHS II and REACH compliant
- Comparable wetting performance to tin/lead process
- Print & dispense grade solder paste available.

Available Alloys

Alloy	Temp °C	Temp °F
42Sn/58Bi	138	280
42Sn/57Bi/1Ag	138	280
96.5Sn/3.0Ag/0.5Cu	217-220	423-428
99.0Sn/0.3Ag/0.7Cu	217-221	423-430
96.5Sn/3.5Ag	221	430
99.3Sn/0.7Cu	227	441
95Sn/5Sb	235-240	455-464
95Sn/5Ag	221-245	430-473

Packaging

- 500 gram jars
- 500 gram cartridges
- 35 or 100 gram syringes
- ProFlow cassettes

Test Results

Test J-STD-004 or other requirements (as stated)	Test Requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No Corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.05%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85 °C, 85% RH @ 168 Hours	IPC-TM-650: 2.6.3.7	L: ≥100 MΩ (No Clean)
Tack Value	IPC-TM-650: 2.4.44	33g
Viscosity - Malcom @ 10 RPM/25 °C (x10 ³ mPa/s)-SAC305 T3/T4	IPC-TM-650: 2.4.34.4	Print: 140-195 Dispensing: 115-160
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

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Printer Operation

The following are general guidelines for stencil printer optimization with NC-560-LF. Some adjustments may be necessary based on your process requirements.

Print Speed: 25-125 mm/sec

Squeegee Pressure: 70-250g/cm of blade

Under Stencil Wipe: Once every 10-25 prints, or as necessary

Stencil Life

>12 hours @ 30-45% RH and 20-25 °C

~ 4 hours @ 45-75% RH and 20-25 °C

Cleaning

NC-560-LF is a no-clean solder paste that does not require cleaning for most SMT assemblies. For applications requiring cleaning, NC-560-LF can be cleaned using flux residue removers such as Inventec Disper 607 and Disper 610.

Recommended Profile

This profile is designed to serve as a starting point for process optimization using NC-560-LF. To achieve better results with voiding or to reduce tombstoning, consider using a longer soaking zone, (170-220 °C) for 60-90 seconds, with a rapid pre-heat stage. If there is evidence of solder de-wetting, consider lowering the peak reflow temperature, or reduce the time above liquidus to <60 seconds.

Amtech Low Oxide Powder Distribution

Micon Size	Type	Pitch Requirements
45 - 75µ	Type-2	24 mil and above
25 - 45µ	Type-3	16 - 24 mil
20 - 38µ	Type-4	12 - 16 mil
15 - 25µ	Type-5	8 - 12 mil
5 - 15µ	Type-6	5 - 8 mil
2 - 11µ	Type-7	< 5 mil

Note: Type-6 and Type-7 may not be available in certain alloys. Other powder distributions are available on request.

Storage

Solder paste should be stored between 3-8 °C (37-46 °F) to obtain the maximum refrigerated shelf life of six months. Unopened solder paste stored at room temperature, 25 °C (77 °F) will have a one month shelf life. Syringes and cartridges should be stored vertically in the refrigerator with the dispensing tip down. Allow 4-8 hours for solder paste to reach an operating temperature of 20-25 °C (68-77 °F). Keep the solder paste container sealed while warming the solder paste to operating temperature. **NEVER FREEZE SOLDER PASTE.**

